

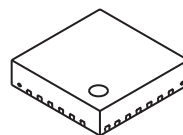
High Power 3 × 5 Antenna Switch MMIC with Integrated Control Logic

Description

The CXG1166AER is a high power antenna switch MMIC for PDC handsets. There are two modes which are TDMA mode and Packet mode.

The CXG1166AER is suited to connect Tx/Rx/Duplexer to one of 4 antennas. This switch has on-chip logic circuit for operation with 4 CMOS inputs. The Sony Junction-gate PHEMT (JPHEMT) process is used for low insertion loss and low voltage operation.

24 pin VQFN (Plastic)



Features

- Low insertion loss: 0.7dB @1.44GHz
- Low loss bypass mode in TDMA
- High linearity: Harmonic < – 60dBc
- CMOS compatible input control
- Small package: 24-pin VQFN (3.3mm × 3.3mm)

Applications

3 × 5 antenna switch for digital cellular such as PDC handsets

Structure

GaAs Junction-gate PHEMT

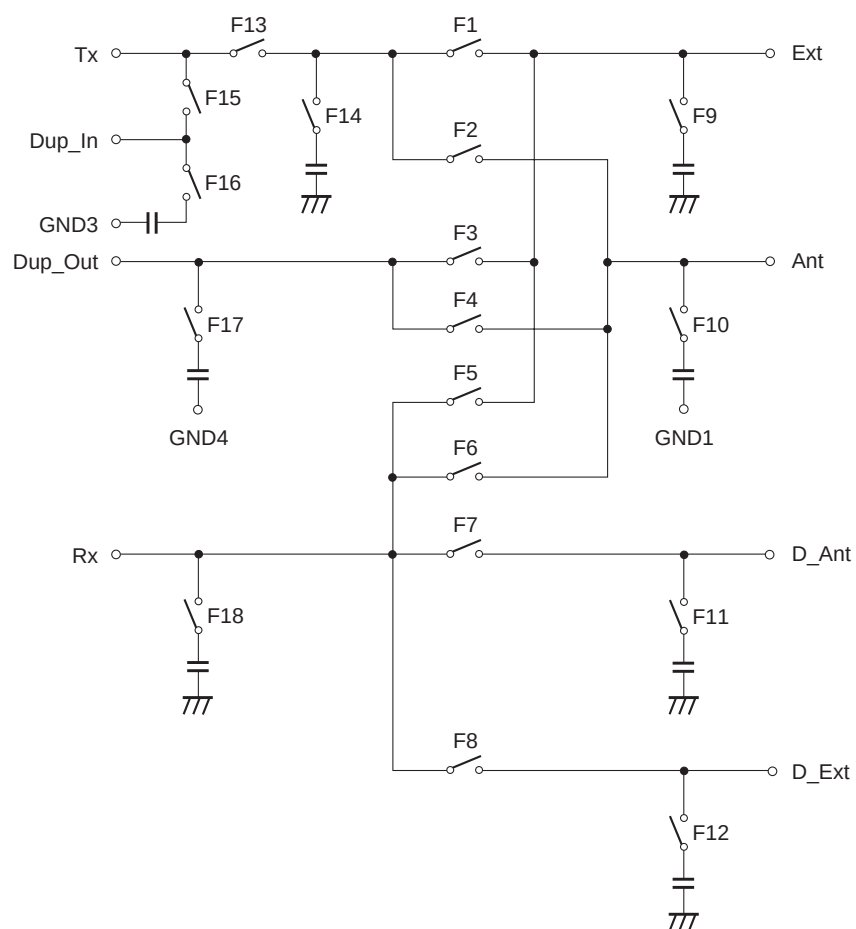
Absolute Maximum Ratings (Ta = 25°C)

• Bias voltage	V _{DD}	7	V
• Control voltage	V _{ctl}	5	V
• Operating temperature	T _{opr}	–35 to +85	°C
• Storage temperature	T _{stg}	–65 to +150	°C

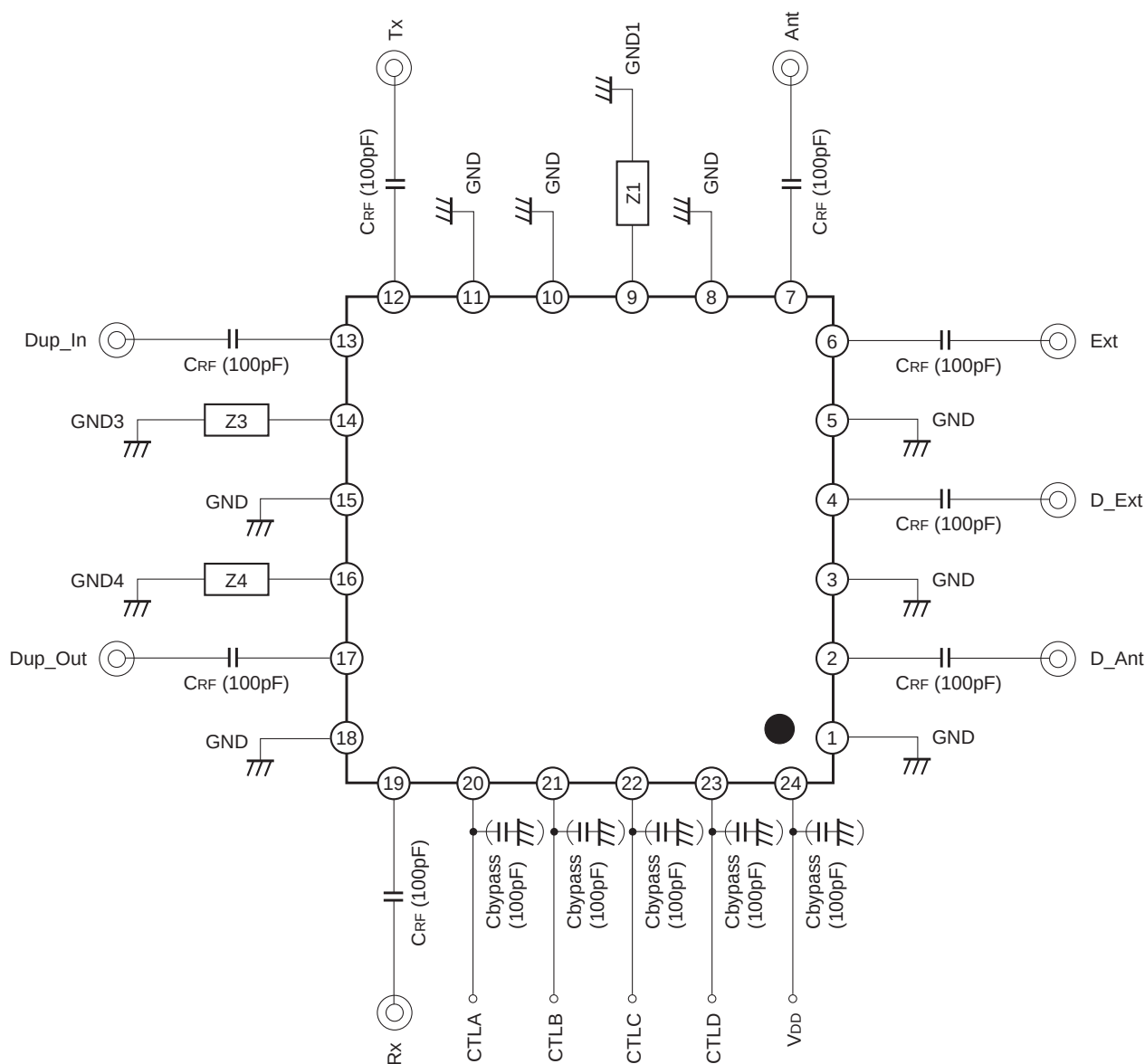
GaAs MMICs are ESD sensitive devices. Special handling precautions are required.

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Block Diagram



Pin Configuration/Recommended Circuit



When using this IC, the following external components should be used:

CRF: This capacitor is used for RF decoupling and must be used for all applications. 100pF is recommended.

Cbypass: This capacitor is used for DC line filtering. 100pF is recommended.

Truth Table

A: Rx/Tx

B: Main/diversity

C: External/antenna

D: TDMA/28.8k

State	On Pass	A	B	C	D	F1	F2	F3	F4	F5	F6	F7	F8	F9	F10	F11	F12	F13	F14	F15	F16	F17	F18
1	Tx – Ext	H	—	L	L	H	L	L	L	L	L	L	L	L	H	H	H	H	L	L	H	H	H
2	Tx – Ant	H	—	H	L	L	H	L	L	L	L	L	L	H	L	H	H	H	L	L	H	H	H
3	Rx – Ext	L	L	L	L	L	L	L	L	H	L	L	L	L	H	H	H	L	H	L	H	H	L
4	Rx – Ant	L	L	H	L	L	L	L	L	L	H	L	L	H	L	H	H	L	H	L	H	H	L
5	Rx – D_Ext	L	H	L	L	L	L	L	L	L	L	L	H	H	H	H	L	L	H	L	H	H	L
6	Rx – D_Ant	L	H	H	L	L	L	L	L	L	L	H	L	H	H	L	H	L	H	L	H	H	L
7	Dup_Out – Ant	—	L	H	H	L	L	L	H	L	H	L	L	H	L	H	H	L	H	H	L	L	L
	Rx – Ant	—	L	H	H	L	L	L	H	L	H	L	L	H	L	H	H	L	H	H	L	L	L
8	Dup_Out – Ant	—	H	H	H	L	L	L	H	L	L	H	L	H	L	L	H	L	H	H	L	L	L
	Rx – D_Ant	—	H	H	H	L	L	L	H	L	L	H	L	H	L	L	H	L	H	H	L	L	L
9	Dup_Out – Ext	—	L	L	H	L	L	H	L	H	L	L	L	L	H	H	H	L	H	H	L	L	L
	Rx – Ext	—	L	L	H	L	L	H	L	H	L	L	L	L	H	H	H	L	H	H	L	L	L
10	Dup_Out – Ext	—	H	L	H	L	L	H	L	L	L	L	H	L	H	H	L	L	H	H	L	L	L
	Rx – D_Ext	—	H	L	H	L	L	H	L	L	L	L	H	L	H	H	L	L	H	H	L	L	L

DC Bias Condition

(Ta = 25°C)

Item	Min.	Typ.	Max.	Unit
V _{DD}	2.7	3.0	3.5	V
V _{ctl} (H)	2.2	3.0	3.5	V
V _{ctl} (L)	0		0.4	V

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Port	Condition	Min.	Typ.	Max.	Unit
Insertion loss	IL	Tx – Ext	*1	—	0.75	1.0	dB
		Tx – Ant	*1	—	0.7	0.95	dB
		Tx – Dup_In	*1	—	0.25	0.5	dB
		Rx – Ext	*2	—	0.65	0.9	dB
		Rx – Ant	*2	—	0.65	0.9	dB
		Rx – D_Ext	*2	—	0.45	0.7	dB
		Rx – D_Ant	*2	—	0.45	0.7	dB
		Dup_Out – Ext	*1, *4	—	0.75	1.0	dB
		Rx – Ext	*2, *5	—	0.8	1.05	dB
		Dup_Out – Ant	*1, *4	—	0.9	1.15	dB
		Rx – Ant	*2, *5	—	0.95	1.2	dB
		Dup_Out – Ext	*1, *4	—	0.45	0.7	dB
		Rx – D_Ext	*2, *5	—	0.5	0.75	dB
		Dup_Out – Ant	*1, *4	—	0.45	0.7	dB
		Rx – D_Ant	*2, *5	—	0.5	0.75	dB
Isolation	ISO.	Tx – Ext	*1	24	30	—	dB
		Tx – Ant	*1	24	30	—	dB
		Tx – Dup_In	*1	19	25	—	dB
		Rx – Ext	*2	24	30	—	dB
		Rx – Ant	*2	24	30	—	dB
		Rx – D_Ext	*2	24	30	—	dB
		Rx – D_Ant	*2	24	30	—	dB
		Dup_Out – Ext	*1, *4	29	35	—	dB
		Rx – Ext	*2, *5	29	35	—	dB
		Dup_Out – Ant	*1, *4	29	35	—	dB
		Rx – Ant	*2, *5	29	35	—	dB
		Dup_Out – Ext	*1, *4	24	30	—	dB
		Rx – D_Ext	*2, *5	24	30	—	dB
		Dup_Out – Ant	*1, *4	24	30	—	dB
		Rx – D_Ant	*2, *5	24	30	—	dB
		Tx – Rx	*1	43	50	—	dB

*1 Pin = 29.5dBm, 0/3V control, V_{DD} = 2.7V to 3.5V, 1,429MHz to 1,453MHz*2 Pin = 10dBm, 0/3V control, V_{DD} = 2.7V to 3.5V, 1,477MHz to 1,501MHz*3 $\pi/4$ -shifted DQPSK, Pin = 29.5dBm, 0/3V control, V_{DD} = 3.0V, 1,429MHz to 1,453MHz,ACP (± 50 kHz) < – 70dBc, ACP (± 100 kHz) < – 75dBc, 2nd harmonics < – 75dBc, 3rd harmonics < – 75dBc

*4 Rx terminal end is OPEN (Pattern cut).

*5 Dup_Out terminal end is OPEN (Pattern cut).

(Ta = 25°C)

Item	Symbol	Port	Condition	Min.	Typ.	Max.	Unit
Harmonics	2fo	Tx – Ext	*3	—	–70	–60	dBc
		Tx – Ant	*3	—	–70	–60	dBc
		Tx – Dup_In	*3	—	–75	–60	dBc
		Dup_Out – Ext (Main)	*3, *4	—	–75	–60	dBc
		Dup_Out – Ext (Div)	*3, *4	—	–70	–60	dBc
		Dup_Out – Ant (Main)	*3, *4	—	–70	–60	dBc
		Dup_Out – Ant (Div)	*3, *4	—	–70	–60	dBc
	3fo	Tx – Ext	*3	—	–67	–60	dBc
		Tx – Ant	*3	—	–67	–60	dBc
		Tx – Dup_In	*3	—	–70	–60	dBc
		Dup_Out – Ext (Main)	*3, *4	—	–67	–60	dBc
		Dup_Out – Ext (Div)	*3, *4	—	–67	–60	dBc
		Dup_Out – Ant (Main)	*3, *4	—	–67	–60	dBc
		Dup_Out – Ant (Div)	*3, *4	—	–67	–60	dBc
ACP	±50kHz	Tx – Ext	*3	—	–70	–57	dBc
		Tx – Ant	*3	—	–70	–57	dBc
		Tx – Dup_In	*3	—	–70	–57	dBc
		Dup_Out – Ext (Main)	*3, *4	—	–70	–57	dBc
		Dup_Out – Ext (Div)	*3, *4	—	–70	–57	dBc
		Dup_Out – Ant (Main)	*3, *4	—	–70	–57	dBc
		Dup_Out – Ant (Div)	*3, *4	—	–70	–57	dBc
	±100kHz	Tx – Ext	*3	—	–73	–65	dBc
		Tx – Ant	*3	—	–73	–65	dBc
		Tx – Dup_In	*3	—	–73	–65	dBc
		Dup_Out – Ext (Main)	*3, *4	—	–73	–65	dBc
		Dup_Out – Ext (Div)	*3, *4	—	–73	–65	dBc
		Dup_Out – Ant (Main)	*3, *4	—	–73	–65	dBc
		Dup_Out – Ant (Div)	*3, *4	—	–73	–65	dBc
Bias current	I _{DD}		V _{DD} = 3.0V		235	350	μA
Control current	I _{ctl}		V _{ctl} (H) = 3.0V		15	30	μA

*1 Pin = 29.5dBm, 0/3V control, V_{DD} = 2.7V to 3.5V, 1,429MHz to 1,453MHz

*2 Pin = 10dBm, 0/3V control, V_{DD} = 2.7V to 3.5V, 1,477MHz to 1,501MHz

*3 $\pi/4$ -shifted DQPSK, Pin = 29.5dBm, 0/3V control, V_{DD} = 3.0V, 1,429MHz to 1,453MHz,

ACP (±50kHz) < –70dBc, ACP (±100kHz) < –75dBc, 2nd harmonics < –75dBc, 3rd harmonics < –75dBc

*4 Rx terminal end is OPEN (Pattern cut).

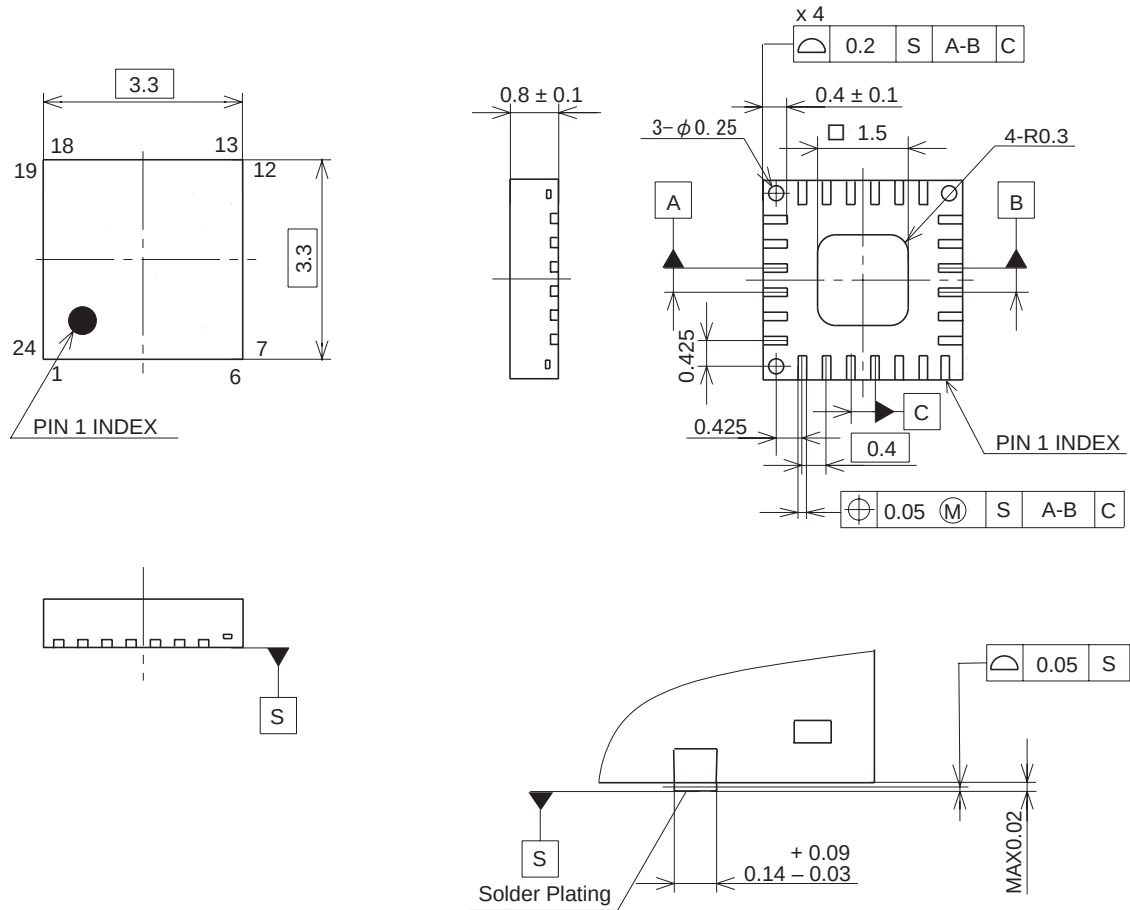
*5 Dup_Out terminal end is OPEN (Pattern cut).

Pin Description

Pin No.	Symbol	Description
2	D_Ant	RF signal output (Use it, connecting capacity.) (100pF is recommended.)
4	D_Ext	RF signal output (Use it, connecting capacity.) (100pF is recommended.)
6	Ext	RF signal output (Use it, connecting capacity.) (100pF is recommended.)
7	Ant	RF signal output (Use it, connecting capacity.) (100pF is recommended.)
12	Tx	RF signal input (Use it, connecting capacity.) (100pF is recommended.)
13	Dup_In	RF signal output (Use it, connecting capacity.) (100pF is recommended.)
17	Dup_Out	RF signal input (Use it, connecting capacity.) (100pF is recommended.)
19	Rx	RF signal input (Use it, connecting capacity.) (100pF is recommended.)
20	CTLA	Logic control A
21	CTLB	Logic control B
22	CTLC	Logic control C
23	CTLD	Logic control D
24	V _{DD}	Power supply input
1, 3, 5, 8, 9, 10, 11, 14, 15, 16, 18	GND	GND

Package Outline Unit: mm

24PIN VQFN (PLASTIC)



TERMINAL SECTION

Note:Cutting burr of lead are 0.05mm MAX.

SONY CODE	VQFN-24P-05
EIAJ CODE	_____
JEDEC CODE	_____

PACKAGE STRUCTURE

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE MASS	0.02g

LEAD PLATING SPECIFICATIONS

ITEM	SPEC.
LEAD MATERIAL	COPPER ALLOY
SOLDER COMPOSITION	Sn-Bi Bi:1-4wt%
PLATING THICKNESS	5-18μm